

# Silicon Carbide (SiC) MOSFET - EliteSiC, 23 mohm, 650 V, M3S, TO-247-4L NTH4L023N065M3S

## Features

- Typical  $R_{DS(on)} = 23 \text{ m}\Omega @ V_{GS} = 18 \text{ V}$
- Ultra Low Gate Charge ( $Q_{G(tot)} = 69 \text{ nC}$ )
- High Speed Switching with Low Capacitance ( $C_{oss} = 153 \text{ pF}$ )
- 100% Avalanche Tested
- This Device is Halide Free and RoHS Compliant with Exemption 7a, Pb-Free 2LI (on second level interconnection)

## Applications

- SMPS, Solar Inverters, UPS, Energy Storages, EV Charging Infrastructure

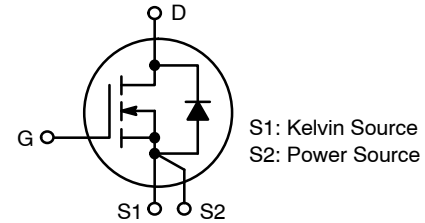
## MAXIMUM RATINGS ( $T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	$V_{DSS}$	650	V
Gate-to-Source Voltage	$V_{GS}$	-8/+22	V
Continuous Drain Current (Note 1)	$I_D$	40	A
Power Dissipation	$P_D$	245	W
Continuous Drain Current (Note 2)	$I_D$	40	A
Power Dissipation	$P_D$	122	W
Pulsed Drain Current (Note 3)	$I_{DM}$	225	A
Continuous Source-Drain Current (Body Diode)	$I_S$	37	A
		23	
Pulsed Source-Drain Current (Body Diode) (Note 3)	$I_{SM}$	166	A
Single Pulse Avalanche Energy (Note 4)	$E_{AS}$	192	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to +175	$^\circ\text{C}$
Lead Temperature for Soldering Purposes (1/8" from case for 10 seconds)	$T_L$	270	$^\circ\text{C}$

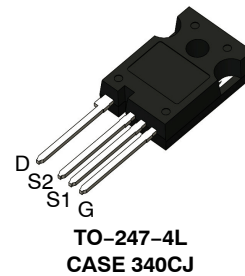
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. 40 A is limited by package. Power chip max drain current is 67 A if limited by max junction temperature.
2. 40 A is limited by package. Power chip max drain current is 47 A if limited by max junction temperature.
3. Repetitive rating, limited by max junction temperature.
4.  $E_{AS}$  of 192 mJ is based on starting  $T_J = 25^\circ\text{C}$ ,  $L = 1 \text{ mH}$ ,  $I_{AS} = 19.6 \text{ A}$ ,  $V_{DD} = 100 \text{ V}$ ,  $V_{GS} = 18 \text{ V}$ .

$V_{(BR)DSS}$	$R_{DS(ON)} \text{ TYP}$	$I_D \text{ MAX}$
650 V	23 m $\Omega$ @ 18 V	40 A



N-CHANNEL MOSFET



## MARKING DIAGRAM



H4L023065M3S = Specific Device Code

A = Assembly Location

Y = Year

WW = Work Week

ZZ = Lot Traceability

## ORDERING INFORMATION

Device	Package	Shipping
NTH4L023N065M3S	TO-247-4L	30 Units / Tube

**THERMAL CHARACTERISTICS**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Note 5)	$R_{\theta JC}$	0.61	°C/W
Thermal Resistance, Junction-to-Ambient (Note 5)	$R_{\theta JA}$	40	

5. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

**RECOMMENDED OPERATING CONDITIONS**

Parameter	Symbol	Value	Unit
Operation Values of Gate-to-Source Voltage	$V_{GSop}$	-5...-3 +18	V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

**ELECTRICAL CHARACTERISTICS** ( $T_J = 25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
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**OFF CHARACTERISTICS**

Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 1\text{ mA}, T_J = 25^\circ\text{C}$	650	-	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$\Delta V_{(BR)DSS} / \Delta T_J$	$I_D = 1\text{ mA}$ , Referenced to $25^\circ\text{C}$	-	89	-	mV/°C
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 650\text{ V}, T_J = 25^\circ\text{C}$	-	-	10	$\mu\text{A}$
		$V_{DS} = 650\text{ V}, T_J = 175^\circ\text{C}$ (Note 7)	-	-	500	$\mu\text{A}$
Gate-to-Source Leakage Current	$I_{GSS}$	$V_{GS} = -8/+22\text{ V}, V_{DS} = 0\text{ V}$	-	-	$\pm 1.0$	$\mu\text{A}$

**ON CHARACTERISTICS**

Drain-to-Source On Resistance	$R_{DS(on)}$	$V_{GS} = 18\text{ V}, I_D = 20\text{ A}, T_J = 25^\circ\text{C}$	-	23	33	m $\Omega$
		$V_{GS} = 18\text{ V}, I_D = 20\text{ A}, T_J = 175^\circ\text{C}$ (Note 7)	-	34	-	
		$V_{GS} = 15\text{ V}, I_D = 20\text{ A}, T_J = 25^\circ\text{C}$	-	29	-	
		$V_{GS} = 15\text{ V}, I_D = 20\text{ A}, T_J = 175^\circ\text{C}$ (Note 7)	-	37	-	
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 10\text{ mA}, T_J = 25^\circ\text{C}$	2	2.8	4	V
Forward Transconductance	$g_{FS}$	$V_{DS} = 10\text{ V}, I_D = 20\text{ A}$ (Note 7)	-	14	-	S

**CHARGES, CAPACITANCES & GATE RESISTANCE**

Input Capacitance	$C_{ISS}$	$V_{DS} = 400\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$ (Note 7)	-	1952	-	pF
Output Capacitance	$C_{OSS}$		-	153	-	
Reverse Transfer Capacitance	$C_{RSS}$		-	13	-	
Total Gate Charge	$Q_{G(TOT)}$	$V_{DD} = 400\text{ V}, I_D = 20\text{ A}, V_{GS} = -3/18\text{ V}$ (Note 7)	-	69	-	nC
Gate-to-Source Charge	$Q_{GS}$		-	19	-	
Gate-to-Drain Charge	$Q_{GD}$		-	18	-	
Gate Resistance	$R_G$	$f = 1\text{ MHz}$	-	4.0	-	$\Omega$

**SWITCHING CHARACTERISTICS**

Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = -3/18\text{ V}, V_{DD} = 400\text{ V}, I_D = 20\text{ A}, R_G = 4.7\text{ }\Omega, T_J = 25^\circ\text{C}$ (Notes 6 and 7)	-	11	-	ns
Turn-Off Delay Time	$t_{d(OFF)}$		-	35	-	
Rise Time	$t_r$		-	15	-	
Fall Time	$t_f$		-	9.6	-	
Turn-On Switching Loss	$E_{ON}$		-	51	-	$\mu\text{J}$
Turn-Off Switching Loss	$E_{OFF}$		-	29	-	
Total Switching Loss	$E_{TOT}$		-	80	-	

# NTH4L023N065M3S

## ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ unless otherwise specified) (continued)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>SWITCHING CHARACTERISTICS</b>						
Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = -3/18\text{ V}$ , $V_{DD} = 400\text{ V}$ , $I_D = 20\text{ A}$ , $R_G = 4.7\ \Omega$ , $T_J = 175^\circ\text{C}$ (Notes 6 and 7)	–	9.6	–	ns
Turn-Off Delay Time	$t_{d(OFF)}$		–	41	–	
Rise Time	$t_r$		–	14	–	
Fall Time	$t_f$		–	12	–	
Turn-On Switching Loss	$E_{ON}$		–	51	–	$\mu\text{J}$
Turn-Off Switching Loss	$E_{OFF}$		–	45	–	
Total Switching Loss	$E_{TOT}$		–	96	–	

## SOURCE-TO-DRAIN DIODE CHARACTERISTICS

Forward Diode Voltage	$V_{SD}$	$I_{SD} = 20\text{ A}$ , $V_{GS} = -3\text{ V}$ , $T_J = 25^\circ\text{C}$	–	3.9	6.0	V
		$I_{SD} = 20\text{ A}$ , $V_{GS} = -3\text{ V}$ , $T_J = 175^\circ\text{C}$ (Note 7)	–	3.6	–	
Reverse Recovery Time	$t_{RR}$	$V_{GS} = -3\text{ V}$ , $I_S = 20\text{ A}$ , $di/dt = 1000\text{ A}/\mu\text{s}$ , $V_{DS} = 400\text{ V}$ , $T_J = 25^\circ\text{C}$ (Note 7)	–	19	–	ns
Charge Time	$t_a$		–	11	–	
Discharge Time	$t_b$		–	8	–	
Reverse Recovery Charge	$Q_{RR}$		–	97	–	nC
Reverse Recovery Energy	$E_{REC}$		–	8.7	–	$\mu\text{J}$
Peak Reverse Recovery Current	$I_{RRM}$		–	11	–	A

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

6. EON/EOFF result is with body diode.

7. Defined by design, not subject to production test.

TYPICAL CHARACTERISTICS

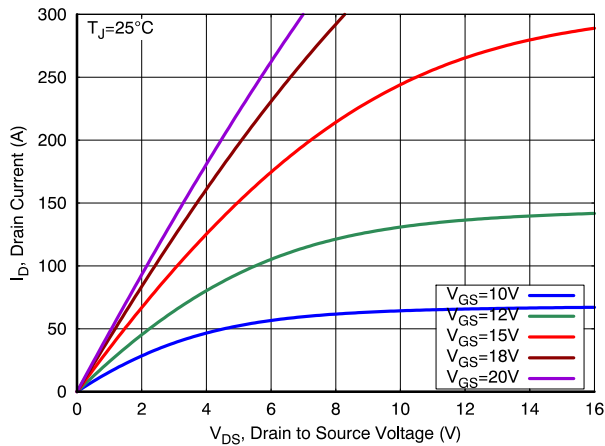


Figure 1. Output Characteristics

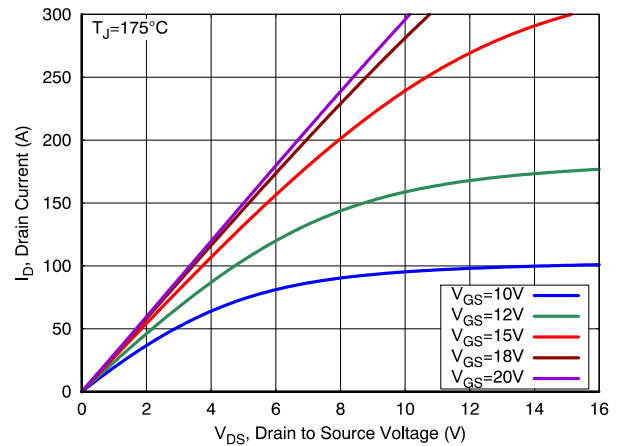


Figure 2. Output Characteristics

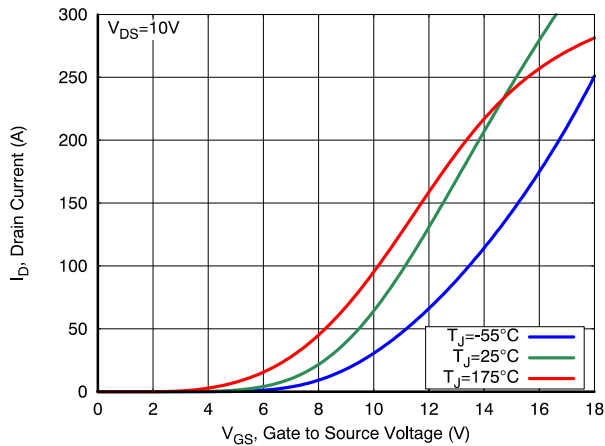


Figure 3. Transfer Characteristics

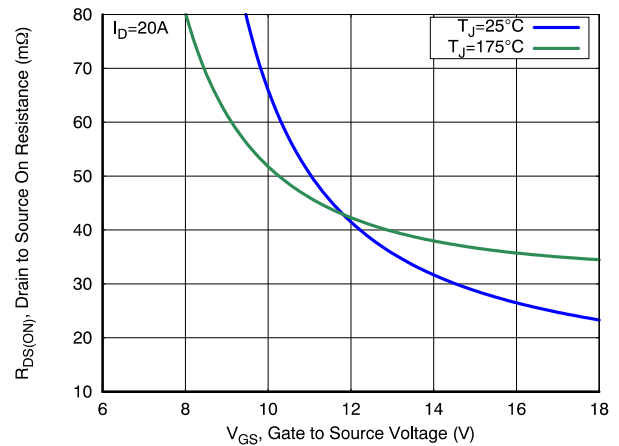


Figure 4. On-Resistance vs. Gate Voltage

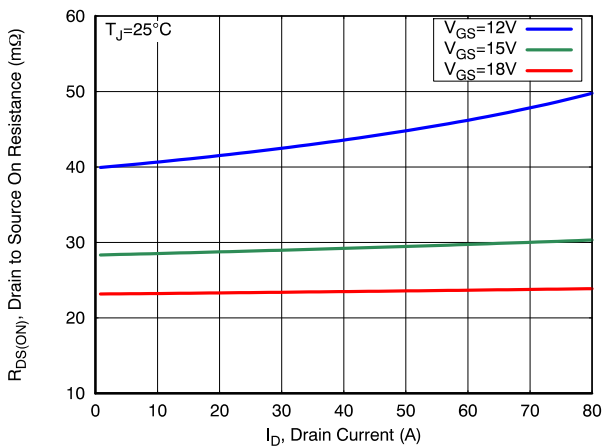


Figure 5. On-Resistance vs. Drain Current

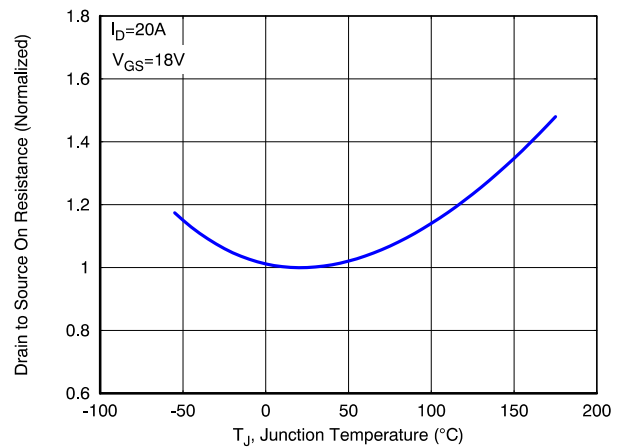


Figure 6. On-Resistance vs. Junction Temperature

TYPICAL CHARACTERISTICS

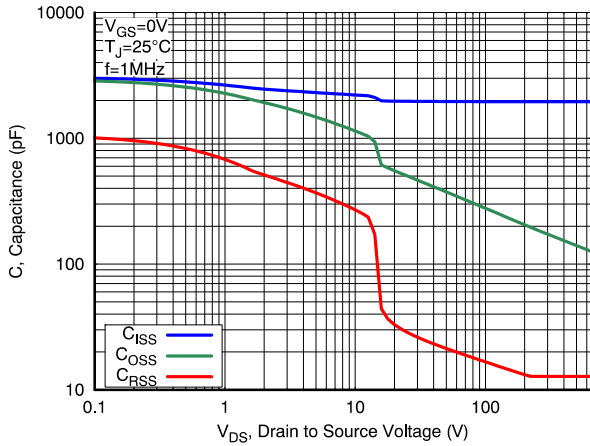


Figure 7. Capacitance Characteristics

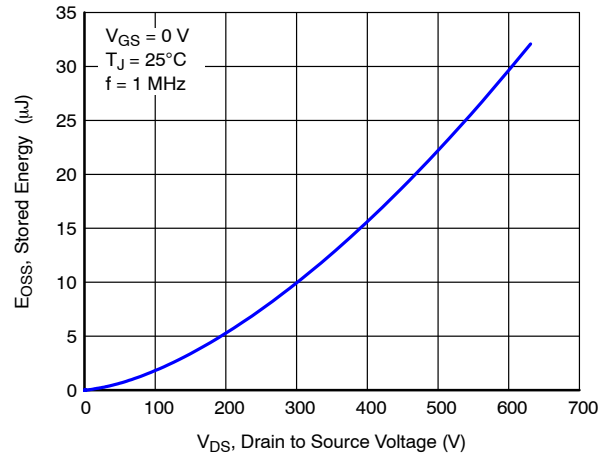


Figure 8. Stored Energy vs Drain to Source Voltage

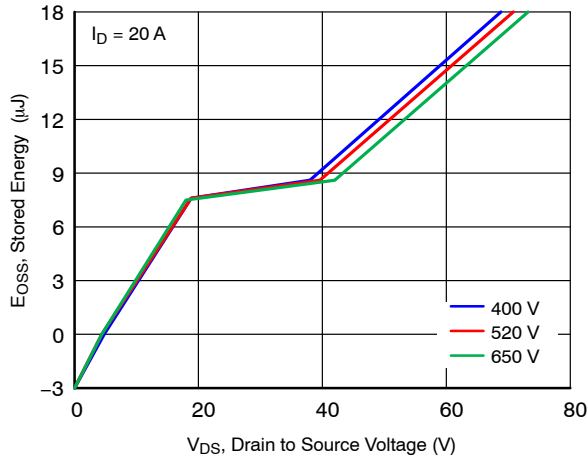


Figure 9. Gate Charge Characteristics

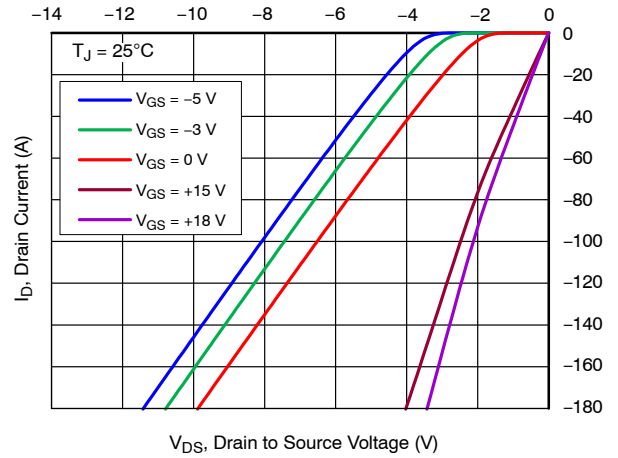


Figure 10. Reverse Conduction Characteristics

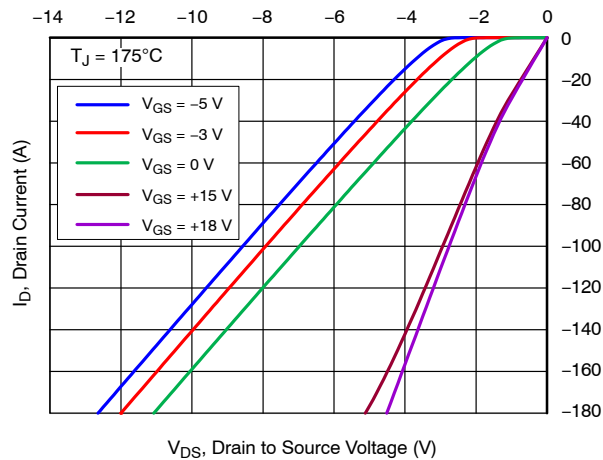


Figure 11. Reverse Conduction Characteristics

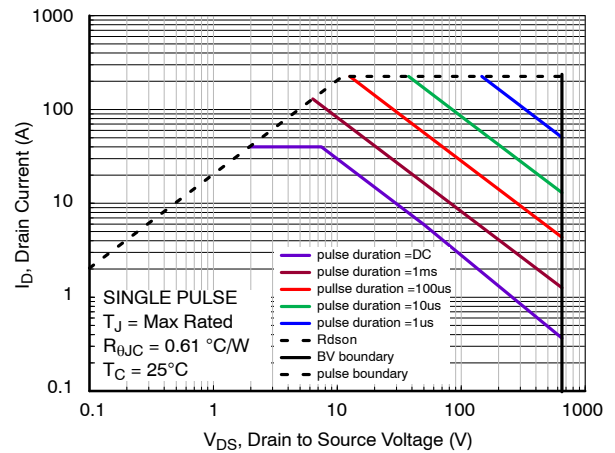


Figure 12. Safe Operating Area

TYPICAL CHARACTERISTICS

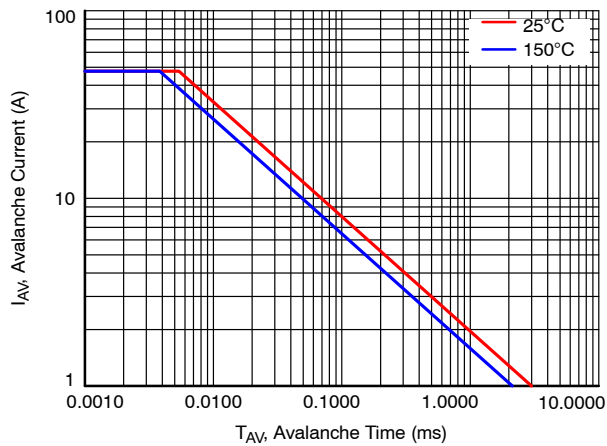


Figure 13. Avalanche Current vs Pulse Time (UIS)

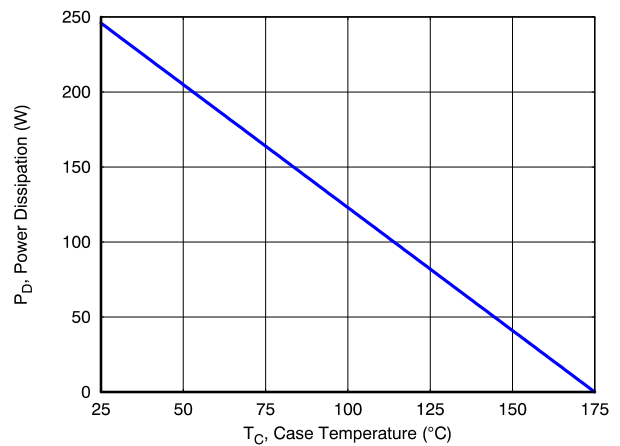


Figure 14. Maximum Power Dissipation vs Case Temperature

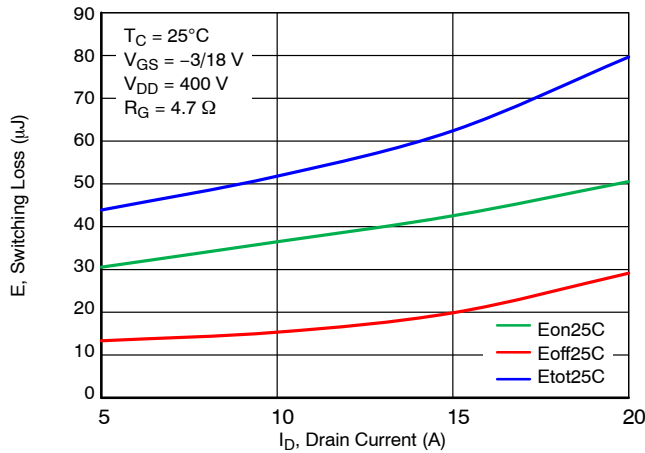


Figure 15. Inductive Switching Loss vs Drain Current

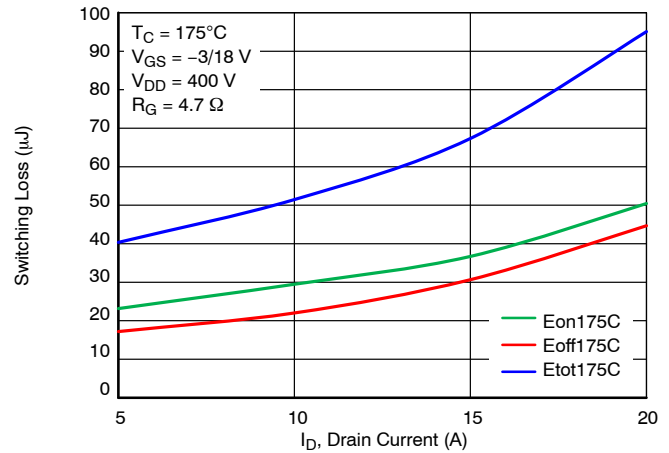


Figure 16. Inductive Switching Loss vs Drain Current

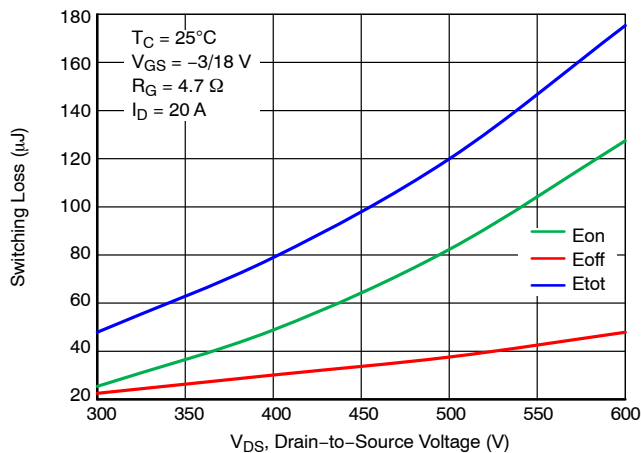


Figure 17. Inductive Switching Loss vs Drain Voltage

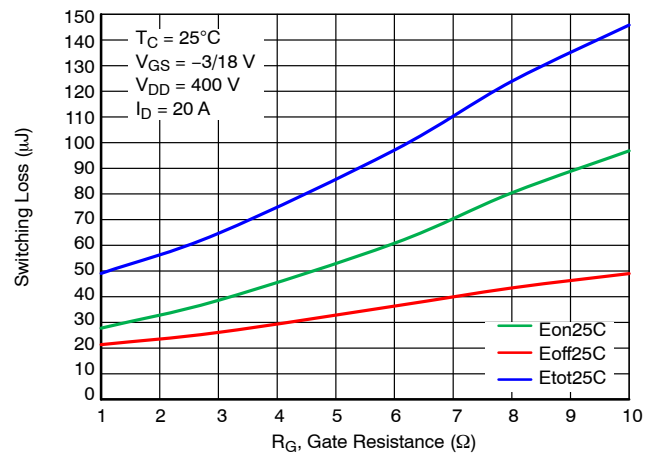


Figure 18. Inductive Switching Loss vs Gate Resistance

TYPICAL CHARACTERISTICS

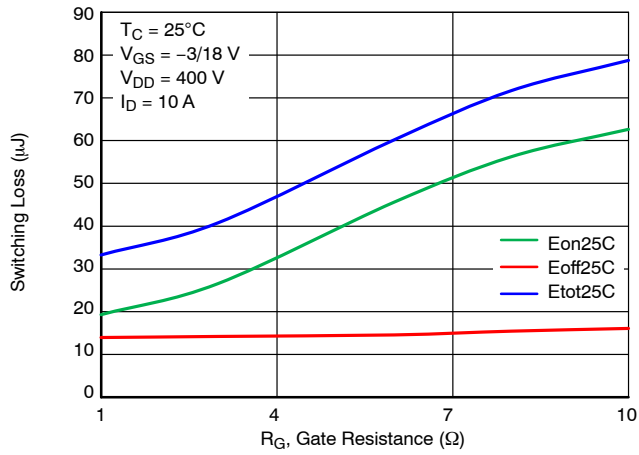


Figure 19. Inductive Switching Loss vs Gate Resistance

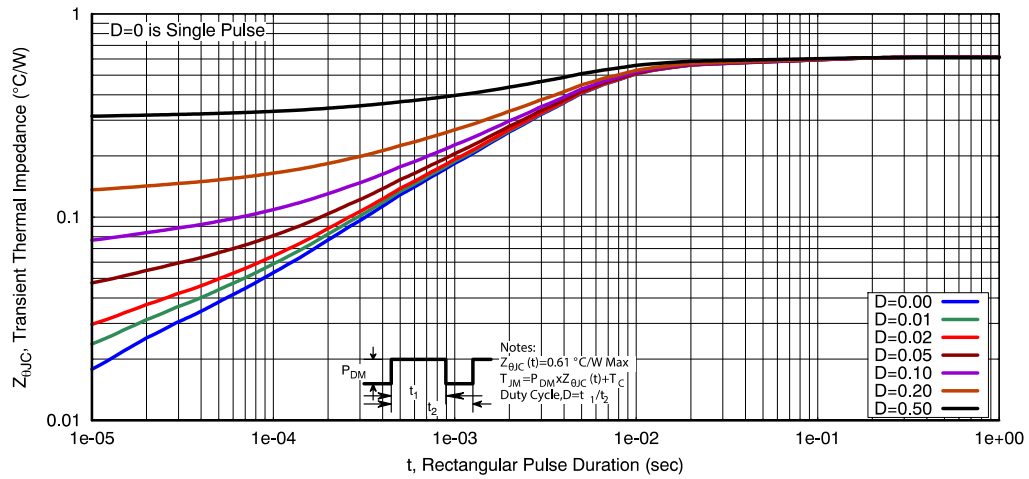


Figure 20. Thermal Response Characteristics

# MECHANICAL CASE OUTLINE

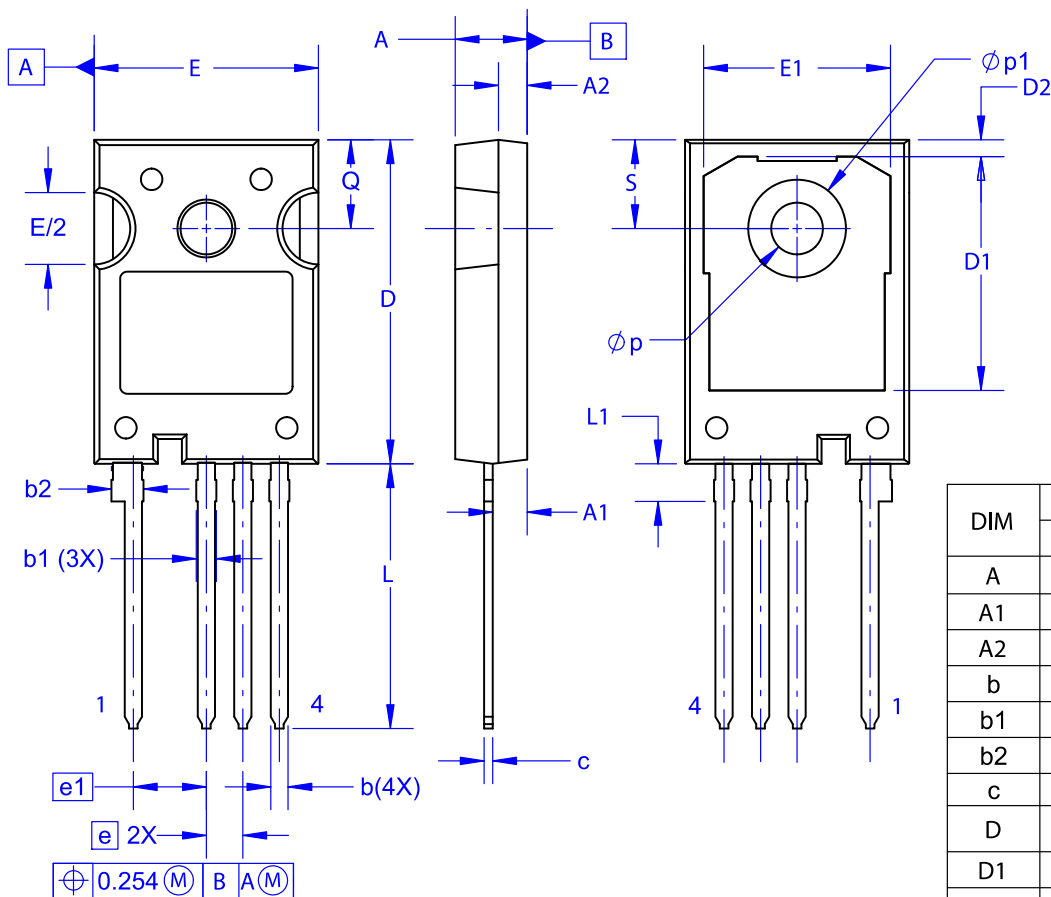
## PACKAGE DIMENSIONS

ON Semiconductor®



TO-247-4LD  
CASE 340CJ  
ISSUE A

DATE 16 SEP 2019



DIM	MILLIMETERS		
	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.10	2.40	2.70
A2	1.80	2.00	2.20
b	1.07	1.20	1.33
b1	1.20	1.40	1.60
b2	2.02	2.22	2.42
c	0.50	0.60	0.70
D	22.34	22.54	22.74
D1	16.00	16.25	16.50
D2	0.97	1.17	1.37
e	2.54 BSC		
e1	5.08 BSC		
E	15.40	15.60	15.80
E1	12.80	13.00	13.20
E/2	4.80	5.00	5.20
L	18.22	18.42	18.62
L1	2.42	2.62	2.82
p	3.40	3.60	3.80
p1	6.60	6.80	7.00
Q	5.97	6.17	6.37
S	5.97	6.17	6.37

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